AMENDMENTS TO THE SPECIFICATION:

Please replace paragraphs [0001], [0003], [0004], [0005], [0007], [0012], [0018], [0025], [0028], [0029], [0030], [0032], [0033], [0034], [0035] and add a new paragraph [0027.1] after paragraph [0027] with the following paragraphs:

[0001] Power supply is a necessary basic equipment for operating various electric ~~equipments~~ equipment or information products ~~as operating~~. Because of the requirement of miniaturization of various electric equipments or information products, ~~the design of~~ small volume and high power ~~is gradually~~ have been a design consideration in the development ~~for~~ of the power supply. In addition to the design consideration, another key point of the power supply is about heat-dispersing. There are many electronic elements positioned in the power supply, and thus when all these electronic elements are operated, a lot of heat will be produced. However, if the produced heat cannot be effectively removed, the temperature within the housing of the power supply will become higher and higher and result in influencing the efficiency of the power supply and the life of the electronic elements.

[0003] Please refer to Fig. 1, which is a sectional drawing showing the structure of the heat-dispersing module of the traditional power supply. Take a power supply with ATX (Advanced Technology expanding) standard as an example. The power supply includes a housing 11, a heat-dispersing fan 12, a printed circuit board 13, a plurality of electronic elements 14 and one or more heat ~~sink~~ sinks 15. The heat-dispersing fan 12 is mounted in the housing 11 for blowing the hot air out of the housing 11 through a vent area (not shown) when the power supply is operating or ~~extracting~~ attracting the air from ~~out~~ outside of the housing 11. In addition, the printed circuit board 13 has a first surface 131 and a second surface 132, wherein on the first surface 131, there are many electronic ~~element~~ elements 14 mounted thereon. Because most of the electronic elements 14 will produce heat when operating in the power supply, ~~it becomes~~ they become the main heat ~~source~~ sources of the power supply. However, the printed circuit board 13 is directly fixed on the bottom surface of the housing 11, and the second surface 132 of the printed circuit board 13 is only about 8.5 mm away from the bottom surface of the housing 11.

[0004] For solving this problem, there always includes one or more heat ~~sink~~ sinks 15 mounted on the first surface 131 of the printed circuit board 13,

wherein the location of the heat sink 15 is preferably to contact the electronic elements 14 radiating large amount of ~~energy~~ heat. The heat sink 15 can conduct the heat generated by the operating electronic elements 14 to the inner space inside the housing 11 for being blown out by the airflow driven by the fan 12 so as to achieve the heat-dispersing efficiency.

[0005] Please refer to Fig. 2, which is a schematic view showing the structure of the housing of the power supply with ATX standard in the prior art. As shown in Fig. 2, the housing 11 of the power supply has six surfaces, wherein the top surface 111 is opposite to the bottom surface 112 and a first side surface 113 is opposite to a second side surface 114. The housing 11 further includes a meshed portion 115, one or more first vent ~~area~~ areas 116 and one or more second vent ~~area~~ areas 117, wherein the meshed portion 115 is formed on the first side surface 113 of the housing 11, the first vent area 116 is formed on the second side surface 114 of the housing 11 and the second vent area 117 is formed on the top surface 111 of the housing 11 and opposite to the first surface 131 (not shown) of the printed circuit board 13. Furthermore, the heat-dispersing fan 12 is mounted ~~above~~ next to the meshed portion 115 and ~~extracts~~ attracts the airflow from the first and second vent areas 116, 117 through the operation thereof so as to maintain the air requirement for the system (not shown) and produce an efficient airflow for dispersing the heat inside the power supply.

[0007] Therefore, how to ~~convince~~ overcome the defects described above and develop a power supply having a better heat-dispersing efficiency is really a priority for the industry.

[0012] Preferably, the heat-dispersing fan is positioned ~~above~~ next to the mashed portion.

[0018] Preferably, a distance between the printed circuit board and the top surface of the housing is ranged from 10 to 50 ~~nm~~ mm.

[0025] Fig. 4 is a sectional drawing showing a heat-dispersing module of a power supply in a ~~preferable~~ preferred embodiment according to the present invention;

[0027.1] Fig. 7 is a sectional drawing showing a heat-dispersing module of a power supply in another preferred embodiment according to the present invention;

[0028] The present invention is a heat-dispersing module of an electronic device. Although the embodiments hereinafter employ the heat-dispersing module of a power supply for explaining the technique of the present invention, the electronic device that can be used in the present invention is not limited to ~~be~~ the power supply only. Any electronic device adaptive to the following technical features is incorporated herein as the reference.

[0029] Please refer to Fig. 4, which is a sectional drawing showing a heat-dispersing module of a power supply in a ~~preferable~~ preferred embodiment according to the present invention. Take the power supply with ATX (Advanced Technology expanding) standard for example. The power supply includes a housing 21, a heat-dispersing fan 22, a printed circuit board 23, a plurality of electronic elements 24 and one or more heat conducting ~~plate~~ plates 25. Among these, the heat-dispersing fan 22 is mounted in the housing 21 for blowing the hot air out of the housing 21 through a vent area (not shown) when the power supply is operating or ~~extracting~~ attracting the external cold air from ~~out~~ outside of the housing 11 for dispersing the heat inside.

[0030] Please refer to Fig. 5, which is a schematic view showing the housing of the power supply in Fig. 4. As shown in Fig. 5, the housing 21 of the power supply has six surfaces, wherein a top surface 211 is opposite to a bottom surface 212 and a first side surface 213 is opposite to a second side surface 214. The housing 21 further includes a meshed portion 215, one or more first vent ~~area~~ areas 216 and one or more second vent ~~area~~ areas 217, wherein the meshed portion 215 is formed on the first side surface 213 of the housing 21, the first vent area 216 is formed on the second side surface 214 of the housing 21 and the second vent area 217 is formed on the top surface 211 of the housing 21. Furthermore, the heat-dispersing fan 22 is mounted ~~above~~ next to the meshed portion 215 so that an airflow can be ~~extracted~~ attracted through the first and second vent areas 216, 217 and exhausted through the meshed portion 215 by ~~mean~~ means of the operation thereof for dispersing the heat inside the power supply.

[0032] The printed circuit board 23 has a first surface 231 and a second surface 232, wherein the first surface 231 is located within the second airflow channel 29, and a number of the electronic elements 24 located on the first surface 231 is significantly larger ~~that~~ than that on the second surface 232. In this embodiment, the distance between the printed circuit board 23 and the top surface 211 of the housing 23 is preferably ranged from 10 to 50 mm.

[0033] Please refer to Fig. 6, which is a schematic view showing the airflow channels when the power supply in Fig. 4 is under operation. The first airflow channel 28 has a sufficient airflow Q2 passing through the second vent area 217 for maintaining the airflow requirement for the system (not shown). As to the second airflow channel 29, it is mainly the heat source region of the power supply. Because the second airflow channel 29 is formed and an effective airflow Q1 passing through the first vent area 216 is no longer influenced by the airflow Q2 passing through the second vent area 217, more effective airflows can be generated to pass the heat source region for further increasing a whole heat-dispersing efficiency of the power supply. As comparing the structure in Fig. 3 with that in Fig. 6, under the same external conditions, the effective airflow Q1 produced in the prior art is approximately 9.3 cfm and the effective airflow Q1 produced in the present invention is approximately 11.5 cfm. Therefore, it can be ~~obvious~~ obviously seen that the technique of the present invention can increase about 23.6% of the effective airflow so that the whole heat-dispersing efficiency can be further improved.

[0034] In addition, please further refer to Fig. 4. For conducting the heat produced by the electronic element 24 on the first surface 231 of the printed circuit board 23, the first surface 231 of the printed circuit board 23 can further set one or more heat conducting ~~plate~~ plates 25. The main function of the heat conducting plate 25 is to conduct the heat produced by the printed circuit board 23 to the bottom surface 212 of the housing 21 for increasing the heat-dispersing area. Moreover, one end of the heat conducting plate 25 can be fixed on the first surface 231 of the printed circuit board 23 and contact with the electronic element 24 radiating larger amount of heat. The other end of the heat conducting plate 25 is contacted with the bottom surface 212 of the housing 21 ~~in a manner of fixing~~ and is fixed through a screw 27. Certainly, the heat at the heat conducting plate 25 also can be diverted by a conducting medium 30 (as shown in Fig. 7) ~~(not shown)~~ located between the other end of the heat conducting plate 25 and the bottom surface 212 of the housing 21

without directly contacting the bottom surface 212. Furthermore, the bottom surface 212 can be made of a material different from or identical to other side surfaces such as any metal or a metal with a better conduction coefficient e.g. aluminum or aluminum alloy. Because the heat is diverted through the contact between the other end of the heat conducting plate 25 and the bottom 212 of the housing 21 or through the conducting medium, the heat produced by the electronic ~~element~~ elements 24 on the first surface 231 of the printed circuit board 23 can be diverted to the bottom surface 222 of the housing 21 through the heat conducting plate 25. Further, because the bottom surface 212 of the housing 21 has a larger heat-dispersing area, the production of a larger heat-dispersing area for the power supply can be achieved by a lower cost by way of the configuration mentioned above.

[0035] Besides, in addition to the heat-dispersing plate, one or more heat ~~sink~~ sinks 26 also can be selectively mounted on the first surface 231 of the printed circuit board 23, like the prior arts. One end of the heat sink 26 can be fixed on the first surface 231 of the printed circuit board 23, and the other end of the heat sink 26 can be selectively ~~set~~ provided with heat-dispersing flanks without contacting with the bottom surface 212 of the housing 21. Because the principle and arrangement of the heat sink 26 are identical to that in the prior art, it will not give unnecessary details here.